



#9/B

Attorney Docket No. 8001-1049

PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Hirokazu MIYAZAKI

Confirmation No. 8771

Serial No. 09/788,596

GROUP 2811

Filed February 21, 2001

Examiner Nitin Parekh

MOUNTING STRUCTURE OF SEMICONDUCTOR
DEVICE AND MOUNTING METHOD THEREOF

12/10/02
Adm H

AMENDMENT AND REPLY UNDER 37 C.F.R. §1.111

Commissioner for Patents

Washington, D.C. 20231

Sir:

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DEC - 2 2002
TC 2800 MAIL ROOM

Responsive to the Official Action of July 3, 2002,
2001, please amend the above-identified application as follows:

IN THE CLAIMS:

Please add the following new claim:

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--17. (new) In combination,
a semiconductor chip which is provided with a plurality
of solder balls;
a wiring substrate which is provided with a plurality
of connection pads; and
an insulating sheet to be positioned between said
semiconductor chip and said wiring substrate, said sheet having a
plurality of leads for electrically connecting said plurality of
solder balls to corresponding ones of said connection pads,
respectively;

C